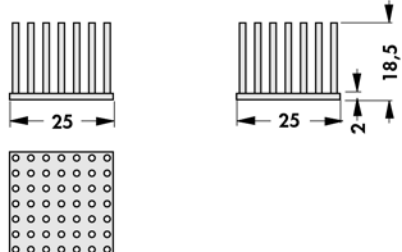
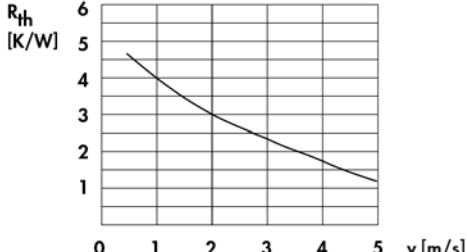
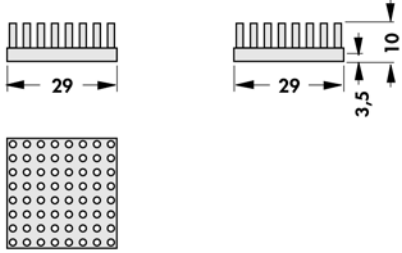
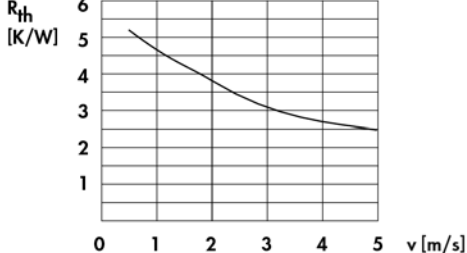
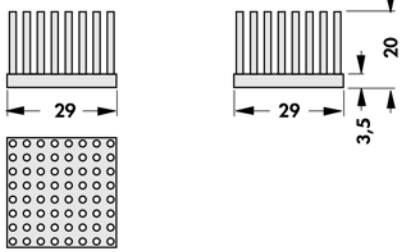
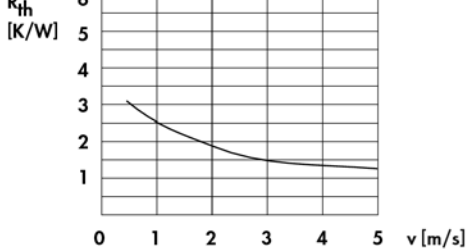
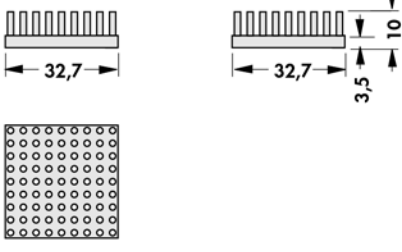
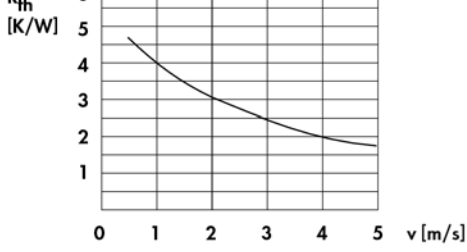
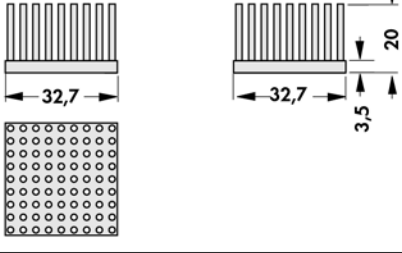
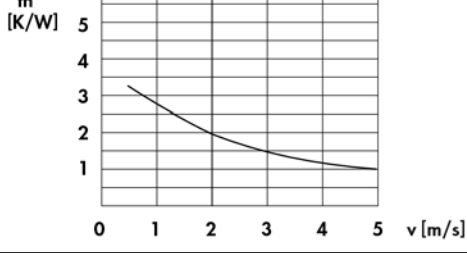
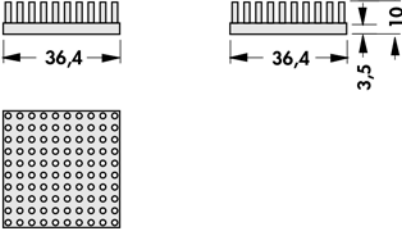
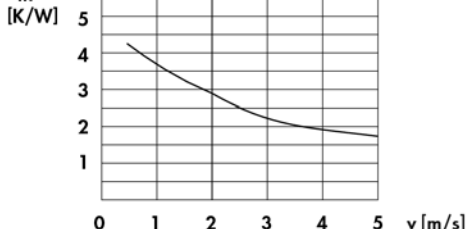


Pin heatsinks

<p>art. no.</p> <p>ICK S 25 x 25 x 18,5 WLF ... 25 x 25 weight: 7 g</p>		
<p>art. no.</p> <p>ICK S 29 x 29 x 10 WLF ... 29 x 29 weight: 11 g</p>		
<p>art. no.</p> <p>ICK S 29 x 29 x 20 WLF ... 29 x 29 weight: 15 g</p>		
<p>art. no.</p> <p>ICK S 32 x 32 x 10 WLF ... 32 x 32 weight: 14 g</p>		
<p>art. no.</p> <p>ICK S 32 x 32 x 20 WLF ... 32 x 32 weight: 19 g</p>		
<p>art. no.</p> <p>ICK S 36 x 36 x 10 WLF ... 36 x 36 weight: 17 g</p>		

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 15
 Thermal conductive paste → E 13
 Processor overview → B 2 - 7

SMD-heatsinks → B 37 - 39
 Mounting material for semiconduct. → E 35 - 39
 Hole pattern → A 21
 Technical introduction → A 2 - 7